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SF2160E

## 2330 MHz SAW Filter



## • RF SAW Filter, 2330 MHz, 60 MHz BW

- 3.0 x 3.0 x 1.4 mm Surface-mount Case
- Complies with Directive 2002/95/EC (RoHS)

#### Absolute Maximum Ratings

Rating	Value	Units
Input Power	+10	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-40 to +85	°C
Component Storage Temperature Range	-50 to +95	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Maximum Soldering Profile, 5 Cycles/10 seconds Maximum	265	°C

#### **Electrical Characteristics**

Characteristic		Sym	Notes	Min	Тур	Max	Units
Center Frequency		f <sub>C</sub>			2330		MHz
Insertion Loss	2300 to 2360 MHz	IL			2.4	3.2	dB
Amplitude Ripple:							
2300 to 2360 MHz					1.1	2	
2300 to 2320 MHz					0.3	1	٩D
2320 to 2340 MHz					0.6	1	dB
2340 to 2360 MHz					0.5	1	
Return Loss	2300 to 2360 MHz			9	9.5		dB
Attenuation Referenced to 0 dB:							
DC to 2085 MHz				25	30		
2097 to 2235 MHz				25	36		dB
2235 to 2256 MHz				15	29		
Case Style			SM3030-6 3 x 3 x 1.4 mm Surface-Mount				
Lid Symbolization, Y=year, WW=week, S=shift, See note 4				•	826 // Y	/WWS	•

#### **Electrical Connections**

Connection	Terminals
Input	2
Output	5
Ground	All others

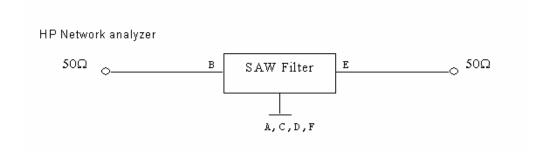


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

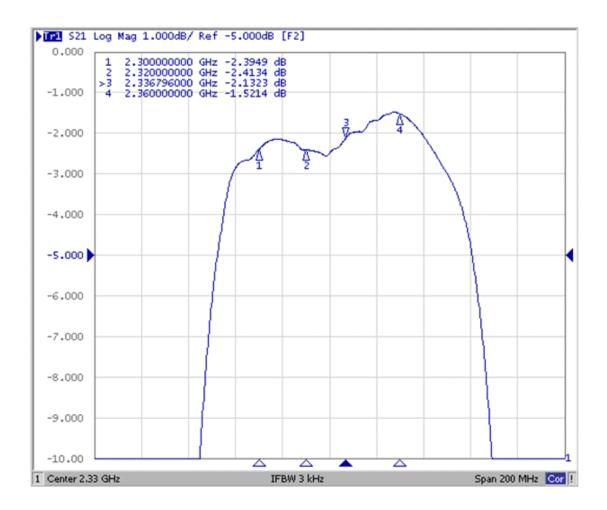
#### NOTES:

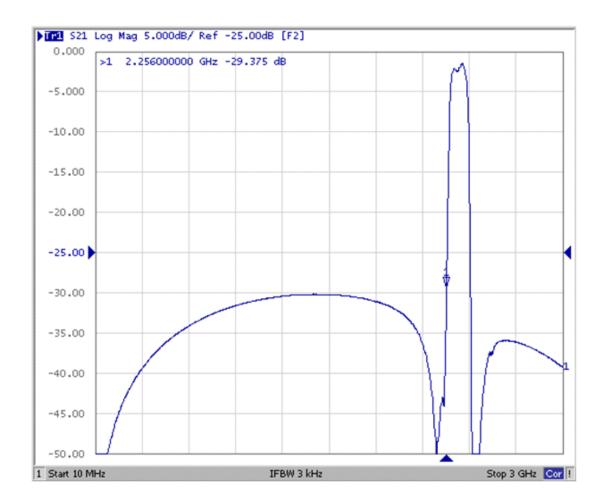
- 1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
- 2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, fc.
- 3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
- 4. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
- 5. The design, manufacturing process, and specifications of this filter are subject to change.
- 6. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
- 7. US and international patents may apply.

## **Testing Environment**

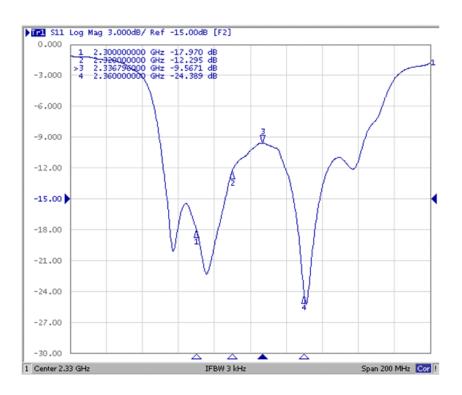


## **Frequency Response**

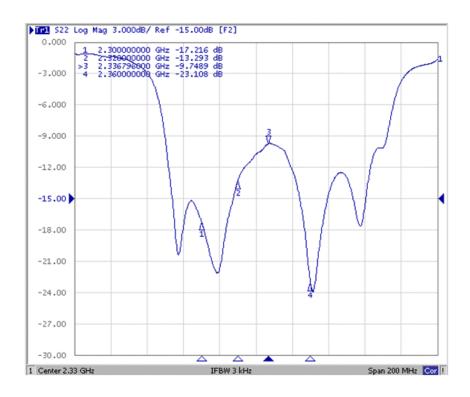




## **S11**

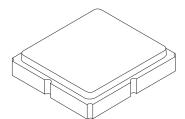


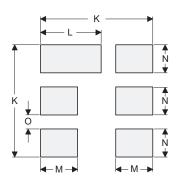
## S22



# **SM3030-6 Case**

# 6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint





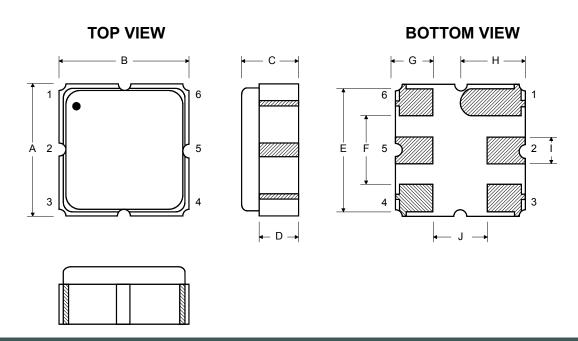
**PCB Footprint Top View** 

## **Case and PCB Footprint Dimensions**

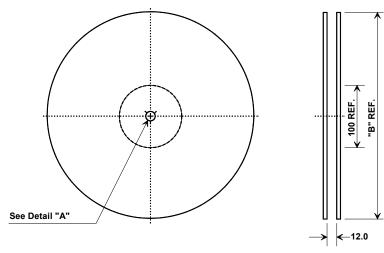
Dimension	mm			Inches			
Difficusion	Min	Nom	Max	Min	Nom	Max	
Α	2.87	3.00	3.13	0.113	0.118	0.123	
В	2.87	3.00	3.13	0.113	0.118	0.123	
С	1.12	1.25	1.38	0.044	0.049	0.054	
D	0.77	0.90	1.03	0.030	0.035	0.040	
E	2.67	2.80	2.93	0.105	0.110	0.115	
F	1.47	1.60	1.73	0.058	0.063	0.068	
G	0.72	0.85	0.98	0.028	0.033	0.038	
Н	1.37	1.50	1.63	0.054	0.059	0.064	
I	0.47	0.60	0.73	0.019	0.024	0.029	
J	1.17	1.30	1.43	0.046	0.051	0.056	
K		3.20			0.126		
L		1.70			0.067		
М		1.05			0.041		
N		0.81			0.032		
0		0.38			0.015		

### **Case Materials**

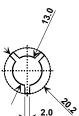
Materials				
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel			
Lid Plating	2.0 to 3.0 µm Nickel			
Body	Al <sub>2</sub> O <sub>3</sub> Ceramic			
Pb Free				



## **Tape and Reel Specifications**



	"B"	Quantity Per Reel
Inches	millimeters	Quality 1 of 1001
7	178	500
13	330	3000



## **COMPONENT ORIENTATION and DIMENSIONS**

Carrier Tape Dimensions	
Ao	3.35 mm
Во	3.35 mm
Ko	1.40 mm
Pitch	8.0 mm
W	12.0 mm

